

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>GARY DALE CARPENTER</td><td>05/18/2011</td></tr><tr><td>ALAN JAMES DRAKE</td><td>05/18/2011</td></tr><tr><td>EREN KURSUN</td><td>05/18/2011</td></tr><tr><td>PHILLIP JOHN RESTLE</td><td>06/01/2011</td></tr></tbody></table>		Name	Execution Date	GARY DALE CARPENTER	05/18/2011	ALAN JAMES DRAKE	05/18/2011	EREN KURSUN	05/18/2011	PHILLIP JOHN RESTLE	06/01/2011
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GARY DALE CARPENTER	05/18/2011										
ALAN JAMES DRAKE	05/18/2011										
EREN KURSUN	05/18/2011										
PHILLIP JOHN RESTLE	06/01/2011										
RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>International Business Machines Corporation</td></tr><tr><td>Street Address:</td><td>New Orchard Road</td></tr><tr><td>City:</td><td>Armonk</td></tr><tr><td>State/Country:</td><td>NEW YORK</td></tr><tr><td>Postal Code:</td><td>10504</td></tr></table>		Name:	International Business Machines Corporation	Street Address:	New Orchard Road	City:	Armonk	State/Country:	NEW YORK	Postal Code:	10504
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PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13156836</td></tr></tbody></table>		Property Type	Number	Application Number:	13156836						
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Application Number:	13156836										
CORRESPONDENCE DATA											
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NAME OF SUBMITTER:	Dimple Pandya										
Total Attachments: 6 source=AUS920110105US1_Assignment#page1.tif											

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ASSIGNMENT

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

INFRASTRUCTURE FOR PERFORMANCE BASED CHIP-TO-CHIP STACKING

and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having:

Serial Number:

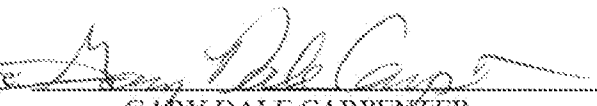
Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned Inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

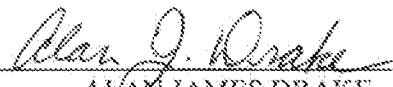
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[Inventor Signature Pages Follow]

Executed by Inventor 1 of 4

Signature:  Date: 05/18/2011
GARY DALE CARPENTER

Executed by Inventor 2 of 4

Signature:  Date: 5/18/2011
ALAN JAMES DRAKE

Executed by Inventor 3 of 4

Signature: _____ Date: _____
EREN KURSUN

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Signature: _____ Date: _____
PHILLIP JOHN RESTLE

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Signature:  _____ Date: 05/18/2011
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Signature: _____ Date: _____
PHILLIP JOHN RESTLE

IBM DOCKET NUMBER: AUS920110105US1

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GARY DALE CARPENTER

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Signature: _____ Date: _____

ALAN JAMES DRAKE

Executed by Inventor 3 of 4

Signature: _____ Date: _____

EREN KURSUN

Executed by Inventor 4 of 4

Signature: Phillip Restle Date: June 1, 2011

PHILLIP JOHN RESTLE

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